IRF640, SiHF640

Vishay Siliconix

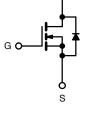
RoHS



Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	200				
R _{DS(on)} (Ω)	V _{GS} = 10 V 0.18				
Q _g (Max.) (nC)	70				
Q _{gs} (nC)	13				
Q _{gd} (nC)	39				
Configuration	Single				





N-Channel MOSFET

FEATURES

- Dynamic dV/dt rating
- Repetitive avalanche rated
- Fast switching
- Ease of paralleling
- Simple drive requirements
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Note

This datasheet provides information about parts that are RoHS-compliant and / or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details.

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION				
Package	TO-220AB			
Lood (Ph) free	IRF640PbF			
Lead (Pb)-free	SiHF640-E3			
SnPb	IRF640			
	SiHF640			

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V _{DS}	200	v
Gate-Source Voltage			V _{GS}	± 20	v
Continuous Drain Current	V _{GS} at 10 V	T _C = 25 °C T _C = 100 °C	1	18	
Continuous Drain Current	V _{GS} at 10 V	T _C = 100 °C	ID	11	A
Pulsed Drain Current ^a	I _{DM}	72			
Linear Derating Factor				1.0	W/°C
Single Pulse Avalanche Energy ^b			E _{AS}	580	mJ
Repetitive Avalanche Current ^a			I _{AR}	18	А
Repetitive Avalanche Energy ^a			E _{AR}	13	mJ
Maximum Power Dissipation $T_{C} = 25 \text{ °C}$			PD	125	W
Peak Diode Recovery dV/dt ^c			dV/dt	5.0	V/ns
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	*0
Soldering Recommendations (Peak temperature) ^d	ering Recommendations (Peak temperature) d for 10 s			300	°C
Maundin a Tanana	6-32 or M3 screw			10	lbf ∙ in
Mounting Torque				1.1	N · m

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11). b. $V_{DD} = 50$ V, starting $T_J = 25$ °C, L = 2.7 mH, $R_g = 25 \Omega$, $I_{AS} = 18$ A (see fig. 12). c. $I_{SD} \le 18$ A, dI/dt ≤ 150 A/µs, $V_{DD} \le V_{DS}$, $T_J \le 150$ °C. d. 1.6 mm from case.

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THERMAL RESISTANCE RATINGS								
PARAMETER	SYMBOL	TYP.	MAX.			UNIT		
Maximum Junction-to-Ambient	R _{thJA}	-	62					
Case-to-Sink, Flat, Greased Surface	R _{thCS}	0.50	-		°C/W			
Maximum Junction-to-Case (Drain)	R _{thJC}	-	1.0					
SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)								
PARAMETER	SYMBOL	TEST CONDITI	ONS	MIN.	TYP.	MAX.	UNIT	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static				•	•	•	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA		200	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I _D = 1 mA	-	0.29	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V$	′ _{GS} , I _D = 250 μA	2.0	-	4.0	V
Gate-Source Leakage	I _{GSS}	V _G	_S = ± 20 V	-	-	± 100	nA
		V _{DS} = 200 V, V _{GS} = 0 V		-	-	25	<u> </u>
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 160 V, \	/ _{GS} = 0 V, T _J = 125 °C	-	-	250	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 11 A ^b	-	-	0.18	Ω
Forward Transconductance	9 _{fs}	V _{DS} = 5	0 V, I _D = 11 A ^b	6.7	-	-	S
Dynamic		•			•		
Input Capacitance	C _{iss}	V	ν _{GS} = 0 V,	-	1300	-	pF
Output Capacitance	C _{oss}	V	$_{\rm DS} = 25 {\rm V},$	-	430	-	
Reverse Transfer Capacitance	C _{rss}	f = 1.0	MHz, see fig. 5	-	130	-	
Total Gate Charge	Qg	$V_{GS} = 10 \text{ V}$ $I_D = 18 \text{ A}, V_{DS} = 160 \text{ V},$ see fig. 6 and 13 ^b		-	-	70	nC
Gate-Source Charge	Q _{gs}			-	-	13	
Gate-Drain Charge	Q _{gd}			-	-	39	
Turn-On Delay Time	t _{d(on)}	V_{DD} = 100 V, I_D = 18 A, R_g = 9.1 $\Omega,~R_D$ = 5.4 $\Omega,~see$ fig. 10 $^{\rm b}$		-	14	-	- ns
Rise Time	t _r			-	51	-	
Turn-Off Delay Time	t _{d(off)}			-	45	-	
Fall Time	t _f			-	36	-	
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	
Internal Source Inductance	L _S			-	7.5	-	– nH
Gate Input Resistance	Rg	f = 1 MHz, open drain		0.5	-	3.6	Ω
Drain-Source Body Diode Characteristic	s			•	•	•	
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	18	
Pulsed Diode Forward Current ^a	I _{SM}			-	-	72	A
Body Diode Voltage	V _{SD}	$T_{J} = 25 \text{ °C}, I_{S} = 18 \text{ A}, V_{GS} = 0 \text{ V} \text{ b}$		-	-	2.0	V
Body Diode Reverse Recovery Time	t _{rr}	$T_J = 25 \text{ °C}, I_F = 18 \text{ A}, dl/dt = 100 \text{ A}/\mu\text{s}^{\text{b}}$		-	300	610	ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	3.4	7.1	μC
Forward Turn-On Time	t _{on}	Intrinsic turn	-on time is negligible (turn	- on is do	minated b	$_{\rm by L_S}$ and	L _D)

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).

b. Pulse width \leq 300 µs; duty cycle \leq 2 %.

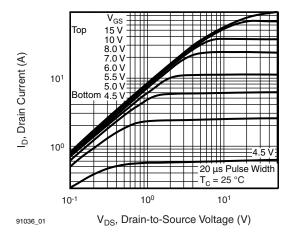
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





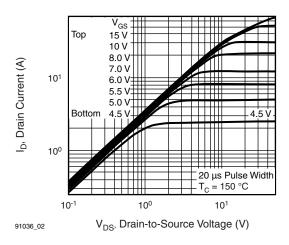
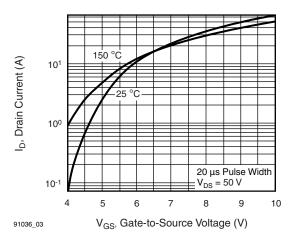


Fig. 2 - Typical Output Characteristics, $T_C = 150 \ ^\circ C$





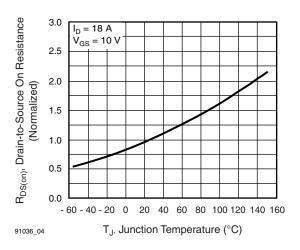


Fig. 4 - Normalized On-Resistance vs. Temperature

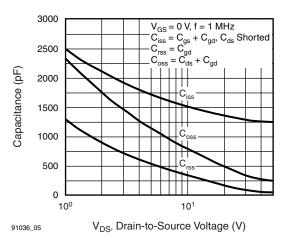


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

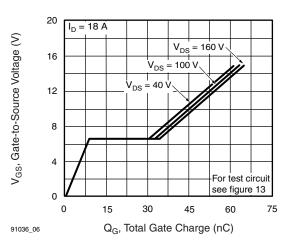


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

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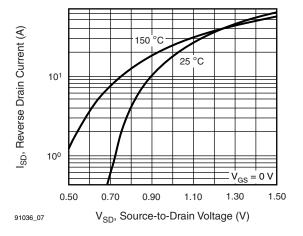


Fig. 7 - Typical Source-Drain Diode Forward Voltage

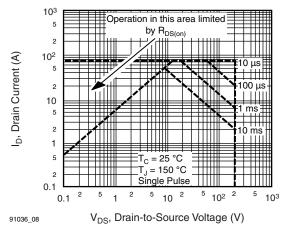


Fig. 8 - Maximum Safe Operating Area

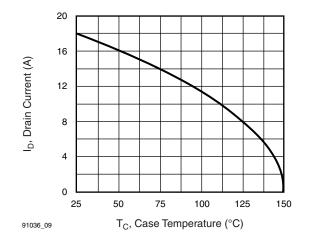


Fig. 9 - Maximum Drain Current vs. Case Temperature

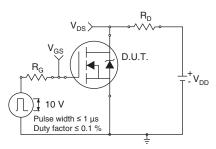


Fig. 10a - Switching Time Test Circuit

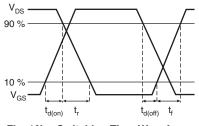
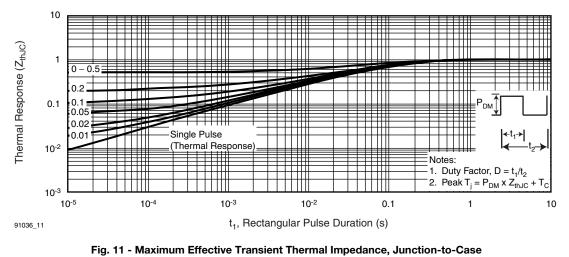


Fig. 10b - Switching Time Waveforms



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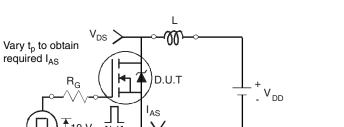
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4





0.01 Ω

Fig. 12a - Unclamped Inductive Test Circuit

tp

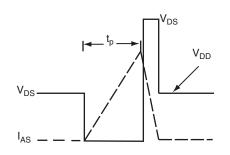


Fig. 12b - Unclamped Inductive Waveforms

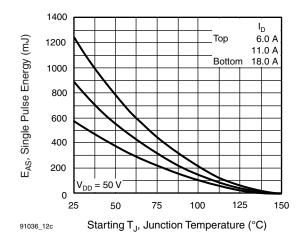


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

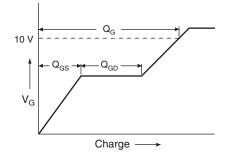


Fig. 13a - Basic Gate Charge Waveform

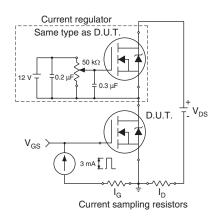


Fig. 13b - Gate Charge Test Circuit

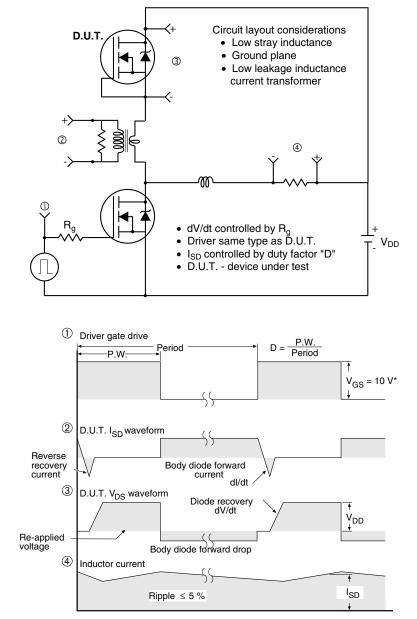
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Peak Diode Recovery dV/dt Test Circuit

* $V_{GS} = 5$ V for logic level devices

Fig. 14 - For N-Channel

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TO-220-1



DIM.	MILLIN	IETERS	INCHES		
DIN.	MIN.	MAX.	MIN.	MAX.	
А	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
E	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØР	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031					

Note

- M^{\star} = 0.052 inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM

Package Picture					
AS	3E	Xi'an			
		IRF 9510 744K AB			

Revison: 14-Dec-15

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